

ABSTRACT

To resolve the problems of the manufacturing costs of an optoelectronic connector, an optoelectronic coupling integrated circuit chip (4) is mounted directly (12) into a package (1) of the connector. This package has an internal shielding metallization and metallizations (11) connected by microconnection techniques to pads (10) of the integrated circuit. The integrated circuit has laser diodes (8) on its surface also connected (13) to the pads (14) of this integrated circuit. These laser diodes are spaced out with respect to one another by a distance corresponding to a distance (21) between the optical fiber terminations (17, 20) in a standardized optical connector (16). The number of elements of the connector is reduced whereas, at the same time, its efficiency in terms of electrical consumption and in terms of transmission quality of a signal is improved.